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Remarks

Entry of the above-noted amendments, reconsideration of the application, and allowance of all claims pending are respectfully requested. By this amendment, claims 1, 6-8, 12-18, 20, 22-25 are amended and claims 29-32 are added. These amendments to the claims constitute a bona fide attempt by applicants to advance prosecution of the application and obtain allowance of certain claims, and are in no way meant to acquiesce to the substance of the rejections. Support for the amendments can be found throughout the specification (e.g., page 6, lines 3-13; and page 7, line 16, to page 8, line 8), drawings (e.g., FIG. 1), and claims and thus, no new matter has been added. Claims 1-32 are pending.

Claim Rejections - 35 U.S.C. §§ 102 and 103:

Claims 1-7, 9-12, and 14-28 are rejected under 35 U.S.C. § 102(b) as being anticipated by Cheon (U.S. Patent No. 6,313,990). Claims 8 and 13 are rejected under U.S.C. § 103(a) as being unpatentable over Cheon in view of Fox, et al. (U.S. Patent No. 5,285,347; "Fox"). These rejections are respectfully, but most strenuously, traversed.

It is well-settled that there is no anticipation unless (1) all the same elements are (2) found in exactly the same situation and (3) are united in the same way to (4) perform the identical function. Since the Office Action's citations to each of the applied references is missing at least one element of each of applicants' independent claims, applicants respectfully submit that the claimed invention is not anticipated by the Office Action's citations to the applied references, as further discussed below.

Applicants respectfully submit that the Office Action's citations to the applied references, with or without modification or combination, assuming, *arguendo*, that the modification or combination of the Office Action's citations to the applied references is

proper, do not teach or suggest one or more elements of the claimed invention, as further discussed below.

For explanatory purposes, applicants discuss herein one or more differences between the Office Action's citations to the applied references and the claimed invention with reference to one or more parts of the applied references. This discussion, however, is in no way meant to acquiesce in any characterization that one or more parts of the Office Action's citations to the applied references correspond to the claimed invention.

Applicants respectfully submit that the Office Action's citations to the applied references do not teach or suggest one or more elements of the claimed invention. A careful reading of the Office Action's citations to the applied references fails to teach or suggest, for example, the one or more heat exchanger components that in major part are operably located outside the rack-mounted computer chassis and serve to reduce the one or more temperatures of the one or more heat producing components supported within the rack-mounted computer chassis, as recited in applicants' independent claim 1.

Cheon (column 4, line 40, to column 5, line 34; FIGS. 1A, 1B, and 2) discloses a heat dissipation device for a personal computer 2. The personal computer 2 has a case 4 that defines an interior space 6. A number of heat-producing components are mounted inside the case 4 in the space 6. A heat dissipation device 36 in subhousing 14 is mounted on the bottom 12 of the case 4. The heat dissipation device 36 has a reservoir 38 for a liquid coolant. The liquid coolant is circulated from the reservoir 38 to the heat transfer devices on the heat-producing components and back to the reservoir 38. Heat transfer fins 44 are mounted on and are in heat exchanging contact with an outside surface of the heat conducting portions of the reservoir 38. The case 4 rests on top of the heat dissipation device 36 in subhousing 14. The case 4 of the personal computer 2 is simply not rack-mountable.

At column 6, line 53, to column 7, line 24, Cheon discloses a heat dissipation device for a rack mounted case. FIGS. 12 and 13 illustrate the rack mounted cases 110 and 110' and the heat dissipation device 36. The heat dissipation device 36 is internal to the rack mounted cases 110 and 110'. The rack mounted cases 110 and 110' have vents 114 and 114' that allow ambient air to pass through the rack mounted cases 110 and 110' to dissipate heat from the heat dissipation device 36. The heat dissipation device 36 is simply not external to the rack mounted case 110 and 110'.

The Office Action's citation to Cheon fails to disclose the one or more heat exchanger components that in major part are operably located outside the rack-mounted computer chassis and serve to reduce the one or more temperatures of the one or more heat producing components supported within the rack-mounted computer chassis.

So, the Office Action's citation to Cheon fails to satisfy at least one of the limitations recited in applicants' independent claim 1.

The shortcomings of Cheon relative to certain elements of the claimed invention have been discussed above. The Office Action proposes a combination of Cheon with Fox. However, Fox does not overcome the deficiency of Cheon. Applicants respectfully submit that the proposed combination of Cheon with Fox fails to provide the required configuration, assuming, *arguendo*, that the combination of Cheon with Fox is proper.

Fox (column 6, line 20; FIGS. 4-5) discloses a circuit board 10 with heat producing electronic components 12. Each of the components 12 may have an attached conventional heat sink 13. A component 14 may produce more heat than any of the other components 12. Therefore, a hybrid heat sink 20 is attached to the component 14. Fans 50 and 54 create airflow over the heat sinks 13 and 20 to dissipate heat from the components 12 and 14. Additionally, cooling liquid may pass through the hybrid heat sink 20 and a radiator 34 to provide greater cooling to the component 14. In one example, the radiator 34 is located

within the path of the airflow from the fans 50 and 54, and thus the fans 50 and 54 are sufficient to cool the radiator 34. In another example, the radiator 34 is unable to be cooled by the fans 50 and 54, and thus an additional fan 58 is employed to cool the radiator. Simply missing from the office actions citation to Fox is any mention of locating the radiator 34 outside of a rack-mounted computer chassis.

The Office Action's citation to Fox fails to disclose the one or more heat exchanger components that in major part are operably located outside the rack-mounted computer chassis and serve to reduce the one or more temperatures of the one or more heat producing components supported within the rack-mounted computer chassis.

So, the Office Action's citation to Fox fails to satisfy at least one of the limitations recited in applicants' independent claim 1.

Furthermore, the Office Action does not allege that the art of record provides any teaching, suggestion, or incentive for modifying the citations to Cheon, and/or Fox to provide the claimed configuration.

For all the reasons presented above with reference to claim 1, claims 1, 18, and 25 are believed neither anticipated nor obvious over the art of the record. The corresponding dependent claims are believed allowable for the same reasons as independent claims 1, 18, and 25, as well as for their own additional characterizations.

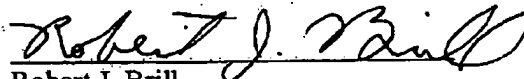
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Withdrawal of the §§ 102 and 103 rejections is therefore respectfully requested.

In view of the above amendments and remarks, allowance of all claims pending is respectfully requested. If a telephone conference would be of assistance in advancing the prosecution of this application, the Examiner is invited to call applicants' attorney.

Respectfully submitted,



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Dated: November 11, 2004

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